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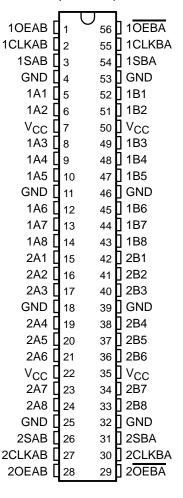
- **Member of the Texas Instruments** Widebus™ Family
- **EPIC** ™ (Enhanced-Performance Implanted **CMOS) Submicron Process**
- Typical V_{OLP} (Output Ground Bounce) $< 0.8 \text{ V at V}_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot) > 2 V at V_{CC} = 3.3 V, T_A = 25°C
- Power Off Disables Inputs/Outputs, **Permitting Live Insertion**
- **Supports Mixed-Mode Signal Operation on** All Ports (5-V Input/Output Voltage With 3.3-V V_{CC})
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883. Method 3015: Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per **JESD 17**
- Bus Hold on Data Inputs Eliminates the **Need for External Pullup/Pulldown** Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

description

This 16-bit bus transceiver and register is designed for 2.7-V to 3.6-V V_{CC} operation.

The SN74LVCH16652A consists of D-type flip-flops and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. The device can be used as two 8-bit transceivers or one 16-bit transceiver.

DGG OR DL PACKAGE (TOP VIEW)



Complementary output-enable (OEAB and OEBA) inputs control the transceiver functions. Select-control (SAB and SBA) inputs select whether real-time or stored data is transferred. A low input level selects real-time data, and a high input level selects stored data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the SN74LVCH16652A.



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description (continued)

Data on the A or B bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs regardless of the levels on the select-control or output-enable inputs. When SAB and SBA are in the real-time transfer mode, it is also possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. When all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last level configuration.

To ensure the high-impedance state during power up or power down, $\overline{\text{OEBA}}$ should be tied to V_{CC} through a pullup resistor and OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

Active bus-hold circuitry holds unused or floating data inputs at a valid logic level.

The SN74LVCH16652A is characterized for operation from -40°C to 85°C.

FUNCTION TABLE

		INP	UTS			DATA	A 1/0†	ODED ATION OD FUNCTION
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1–A8	B1-B8	OPERATION OR FUNCTION
L	Н	H or L	H or L	Х	Х	Input	Input	Isolation
L	Н	1	↑	Χ	Х	Input	Input	Store A and B data
Х	Н	1	H or L	Х	Х	Input	Unspecified [‡]	Store A, hold B
Н	Н	\uparrow	\uparrow	X‡	Х	Input	Output	Store A in both registers
L	Х	H or L	1	Х	Х	Unspecified [‡]	Input	Hold A, store B
L	L	1	\uparrow	X	χ‡	Output	Input	Store B in both registers
L	L	Х	X	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	X	Н	Output	Input	Stored B data to A bus
Н	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
Н	Н	H or L	Χ	Н	Х	Input	Output	Stored A data to B bus
Н	L	H or L	H or L	Н	Н	Output	Output	Stored A data to B bus and stored B data to A bus

[†] The data-output functions may be enabled or disabled by a variety of level combinations at OEAB or OEBA. Data-input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

Select control = H; clocks must be staggered to load both registers.



[‡] Select control = L; clocks can occur simultaneously.

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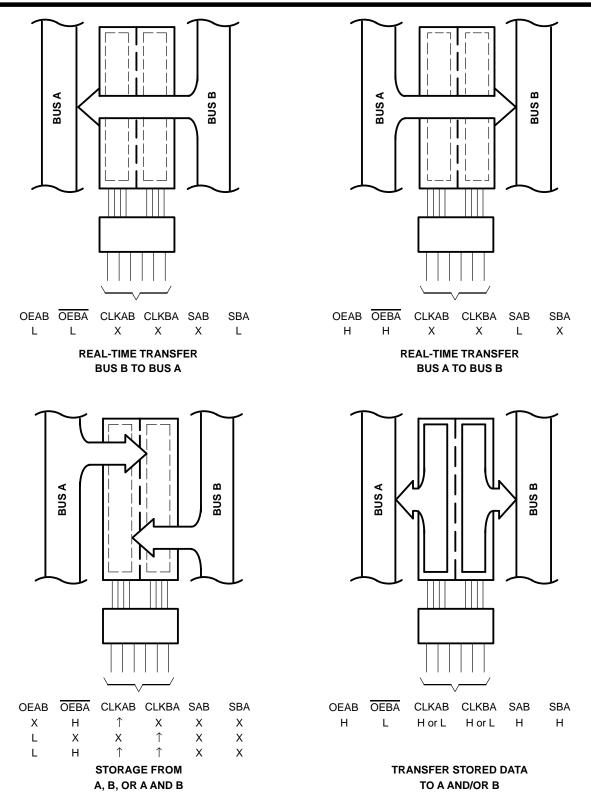
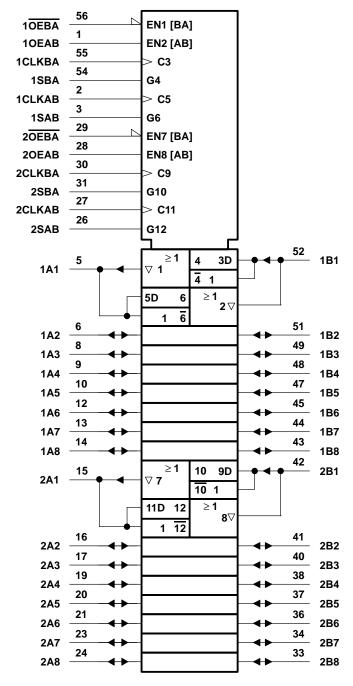


Figure 1. Bus-Management Functions



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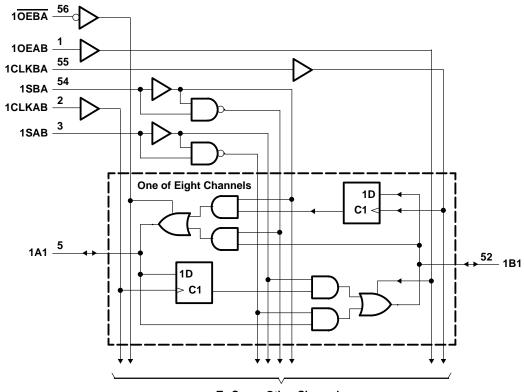
logic symbol†



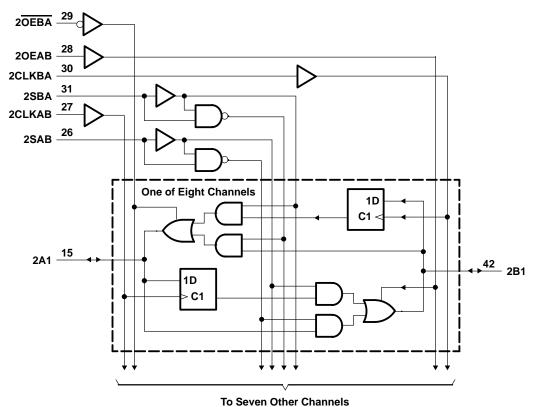
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



To Seven Other Channels





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 6.5 V
Input voltage range, V _I : Except I/O ports (see Note 1)	
I/O ports (see Notes 1 and 2)	-0.5 V to V _{CC} + 0.5 V
Voltage range applied to any output in the high-impedance or power-off state, VO	
(see Note 1)	–0.5 V to 6.5 V
Voltage range applied to any output in the high or low state, VO	
(see Notes 1 and 2)	-0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) (see Note 2)	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 3): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T _{sta}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. The value of V_{CC} is provided in the recommended operating conditions table.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
V/00	Supply voltage Operating Data retention of		2	3.6	V	
VCC			1.5		٧	
V_{IH}	High-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		V	
V_{IL}	Low-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	V	
٧ _I	Input voltage		0	5.5	V	
v _O	Output voltage	High or low state	0	VCC	V	
	Output voltage	3 state	0	5.5	l v	
lavi	I limb laved autout avenue	V _{CC} = 2.7 V		-12	mA	
ЮН	High-level output current	V _{CC} = 3 V		-24	IIIA	
la.	Law law law day tawaran	V _{CC} = 2.7 V		12	mA	
IOL	Low-level output current VCC = 3 V			24	IIIA	
Δt/ΔV	Input transition rise or fall rate		0	10	ns/V	
T _A	Operating free-air temperature	_	-40	85	°C	

NOTE 4: Unused inputs must be held high or low to prevent them from floating.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		VCC	MIN	TYP [†]	MAX	UNIT
. V		$I_{OH} = -100 \mu\text{A}$		2.7 V to 3.6 V	V _{CC} -0.2			V
		J 42 m/s		2.7 V	2.2			
Vон		I _{OH} = -12 mA		3 V	2.4			V
		$I_{OH} = -24 \text{ mA}$		3 V	2.2			
		I _{OL} = 100 μA		2.7 V to 3.6 V			0.2	
VOL		I _{OL} = 12 mA	2.7 V			0.4	V	
		I _{OL} = 24 mA		3 V			0.55	
lį	Control inputs	V _I = 0 to 5.5 V		3.6 V			±5	μΑ
	A or B ports	V _I = 0.8 V	= 0.8 V		75			
I _I (hold)		V _I = 2 V		3 V	– 75			μΑ
		$V_{I} = 0 \text{ to } 3.6 \text{ V}^{\ddagger}$		3.6 V			±500	
l _{off}		V_I or $V_O = 5.5 V$		0			±10	μΑ
loz§		V _O = 0 to 5.5 V		3.6 V			±10	μΑ
		$V_I = V_{CC}$ or GND	1- 0	3.6 V			20	
lcc		$3.6 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}^{\P}$	IO = 0	3.6 V	20		20	μΑ
∆lcc		One input at V _{CC} – 0.6 V,	Other inputs at V _{CC} or GND	2.7 V to 3.6 V			500	μΑ
Ci	Control inputs	V _I = V _{CC} or GND		3.3 V		5	·	pF
C _{io}	A or B ports	$V_O = V_{CC}$ or GND		3.3 V		8		pF

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		UNIT	
			MIN	MAX	MIN	MAX	
fclock	Clock frequency			150		150	MHz
t _W	Pulse duration, CLK high or low		3.3		3.3		ns
t _{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	Data high or low	3		3.4	, and the second	ns
t _h	Hold time, A or B after CLKAB↑ or CLKBA↑	Data high or low	0.2	·	0	, and the second	ns

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	
f _{max}			150		150		MHz
	A or B	B or A	1.4	6.3		6.4	
t _{pd}	CLKAB or CLKBA	A or B	2.4	6.4		7.3	ns
	SAB or SBA	B or A	1.9	7.4		8.8	
t _{en}	OE or OE	A or B	1.6	6.3		6.6	ns
t _{dis}	OE or OE	A or B	1.2	6.2		6.6	ns



[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C. ‡ This is the bus-hold maximum dynamic current required to switch the input from one state to another.

[§] For I/O ports, the parameter IOZ includes the input leakage current.

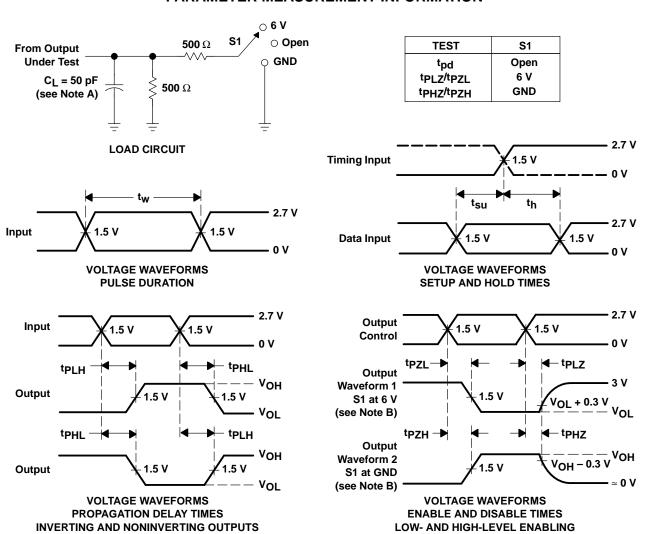
This applies in the disabled state only.

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operating characteristics, V_{CC} = 3.3 V, T_A = 25°C

PARAMETER			TEST CO	ONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C _L = 0,	f = 10 MHz	55	٠,
		Outputs disabled			12	p⊢

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpzL and tpzH are the same as ten.
- F. tpLZ and tpHZ are the same as tdis.
- G. tplH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



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